

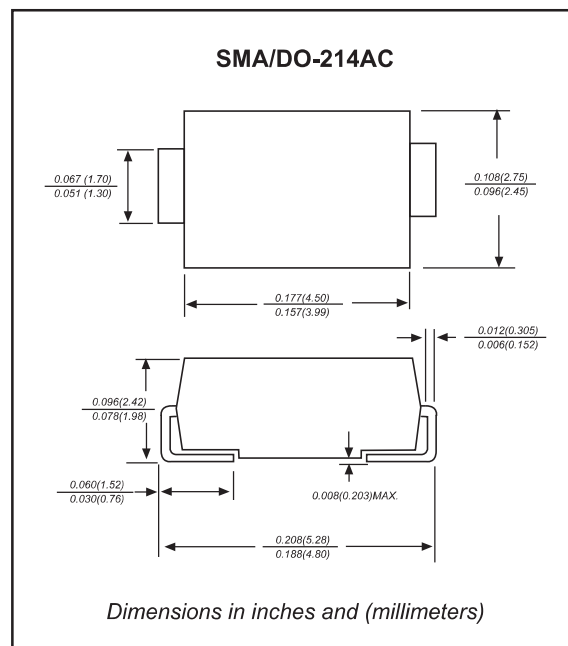
Features

- Glass passivated chip
- Built-in strain relief
- Low inductance
- High peak reverse power dissipation
- Low reverse leakage
- For use in stabilizing and clipping *with high power rating*
- Compliant to Halogen-free

Mechanical data

- Case: DO-214AC Molded plastic
- Lead: Solderable per MIL-STD-750, method 2026
- Epoxy: UL 94V-0 rate flame retardant
- Polarity: Color band denotes cathode end
- Mounting position: Any

Package outline



Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbols	Value	Unit
DC Power dissipation at $T_L = 75^\circ\text{C}$	P_D	3.0	W
Maximum forward voltage at $I_F=200\text{mA}$	V_F	1.2	V
Junction temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Part Number	Device Marking Code	Nominal Zener Voltage @ I_T			$I_{ZT}(\text{mA})$	Maximum Zener Impedance			Maximum Reverse Leakage Current		Maximum DC Zener Current
		$V_{Z\text{AVE}}(\text{V})$	$V_{Z\text{MIN}}(\text{V})$	$V_{Z\text{MAX}}(\text{V})$		$Z_{ZT\text{MAX}}(\Omega)@I_{ZT}$	$Z_{ZK\text{MAX}}(\Omega)@I_{ZK}$	$I_{ZK}(\text{mA})$	$I_R(\mu\text{A})@V_R$	$V_R(\text{V})$	
SZ55D7	3Z270A	270	256.5	283.5	2.6	3300	9500	0.25	0.5	229.5	9.3

Rating and characteristic curves

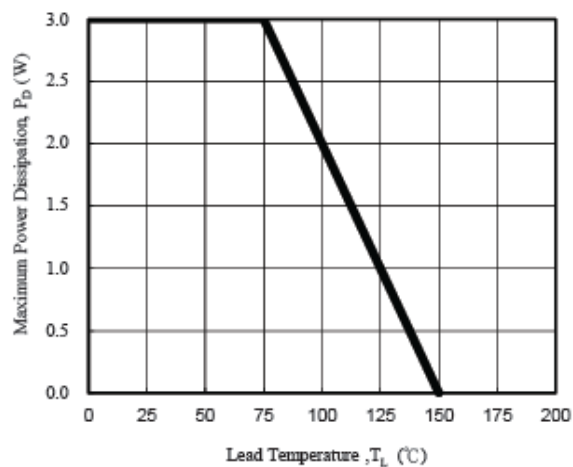


Fig. 1 - Power Temperature Derating Curve

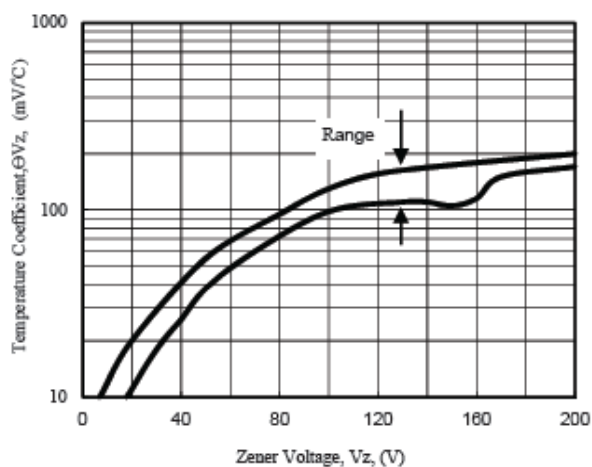


Fig. 2 - Temperature Coefficients v.s. Zener Voltage

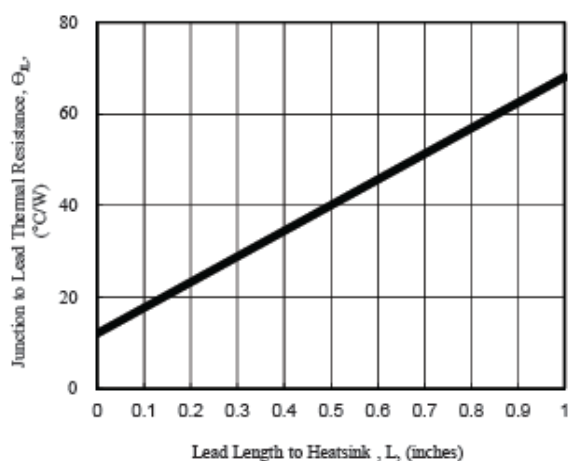


Fig. 3 - Typical Thermal Resistance v.s. Lead Length

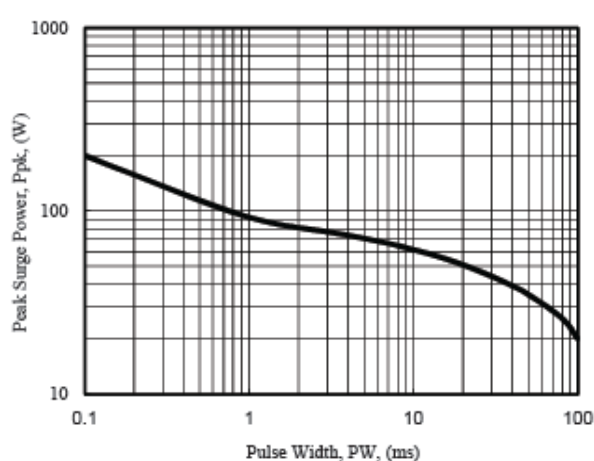


Fig. 4 - Maximum Surge Power

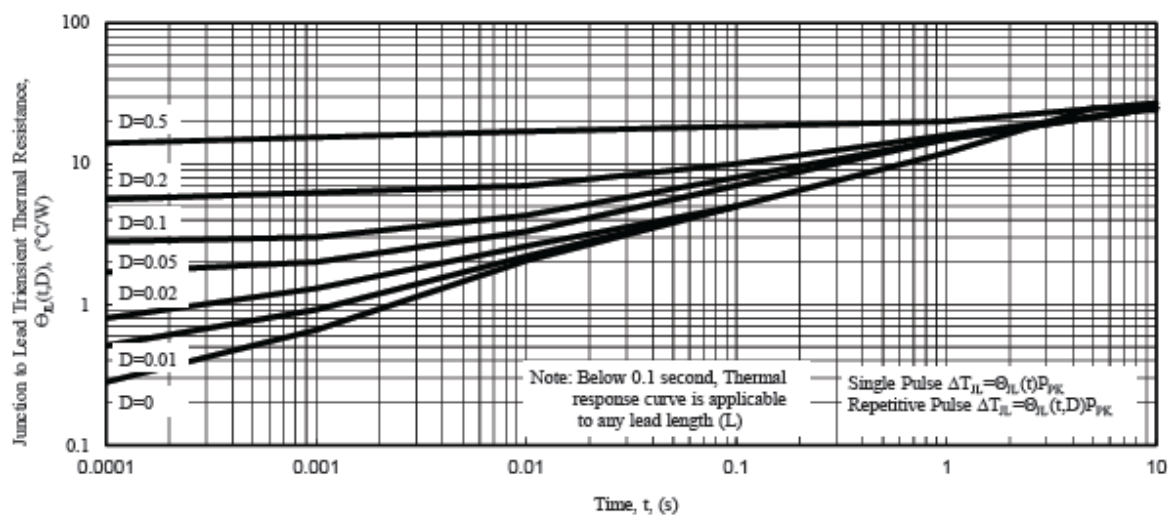
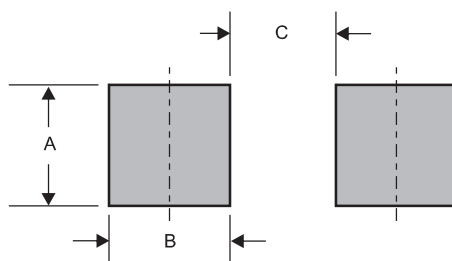


Fig. 5 - Typical Thermal Response L, Lead Length=3/8inch

Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)